# **5 V Differential PECL to TTL Translator**

## Description

The MC10ELT/100ELT21 is a differential PECL to TTL translator. Because PECL (Positive ECL) levels are used, only +5 V and ground are required. The small outline 8-lead package and the single gate of the ELT21 makes it ideal for those applications where space, performance and low power are at a premium.

The V<sub>BB</sub> pin, an internally generated voltage supply, is available to this device only. For single-ended input conditions, the unused differential input is connected to V<sub>BB</sub> as a switching reference voltage. V<sub>BB</sub> may also rebias AC coupled inputs. When used, decouple V<sub>BB</sub> and V<sub>CC</sub> via a 0.01  $\mu$ F capacitor and limit current sourcing or sinking to 0.5 mA. When not used, V<sub>BB</sub> should be left open.

The 100 Series contains temperature compensation.

## Features

- 3.5 ns Typical Propagation Delay
- 24 mA TTL Output
- Flow Through Pinouts
- Operating Range:  $V_{CC} = 4.75$  V to 5.25 V with GND = 0 V
- Q Output Will Default LOW with Inputs Left Open or < 1.3 V
- Pb-Free Packages are Available



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HLT21

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## MARKING DIAGRAMS\*

1 1 1



D SUFFIX CASE 751



DT SUFFIX

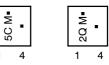
CASE 948R



8 A A A A

KLT21

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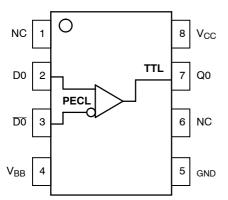
DFN8 MN SUFFIX CASE 506AA

Н	= MC10	А	= Assembly Location
Κ	= MC100	L	= Wafer Lot
5C	= MC10	Υ	= Year
2Q	= MC100	W	= Work Week
М	= Date Code	•	= Pb-Free Package

(Note: Microdot may be in either location) \*For additional marking information, refer to Application Note AND8002/D.

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.





#### Table 1. PIN DESCRIPTION

Pin	Function			
Q0	TTL Outputs			
D0, <u>DO</u>	PECL Differential Outputs			
V <sub>BB</sub>	Reference Voltage Output			
V <sub>CC</sub>	Positive Supply			
GND	Ground			
NC	No Connect			
EP	Exposed pad must be connected to a sufficient thermal conduit. Electrically connect to the most negative supply or leave floating open.			

#### Table 2. ATTRIBUTES

Charact	Value							
Internal Input Pulldown Resisto	50 k $\Omega$							
Internal Input Pullup Resistor		N	/A					
ESD Protection	> 2	kV						
Moisture Sensitivity, Indefinite	Moisture Sensitivity, Indefinite Time Out of Drypack (Note 1)							
	SOIC-8 TSSOP-8 DFN8	Level 1 Level 1 Level 1	Level 1 Level 3 Level 1					
Flammability Rating	Flammability Rating Oxygen Index: 28 to 34							
Transistor Count	81 De	evices						
Meets or exceeds JEDEC Spec	c EIA/JESD78 IC Latchup Test	Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test						

1. For additional information, see Application Note AND8003/D.

#### Table 3. MAXIMUM RATINGS

Symbol	Parameter	Condition 1	Condition 2	Rating	Unit
V <sub>CC</sub>	PECL Power Supply	GND = 0 V		7	V
V <sub>IN</sub>	PECL Input Voltage	GND = 0 V	$V_{I} \leq V_{CC}$	0 to 6	V
I <sub>BB</sub>	V <sub>BB</sub> Sink/Source			± 0.5	mA
ТА	Operating Temperature Range			-40 to +85	°C
T <sub>stg</sub>	Storage Temperature Range			-65 to +150	°C
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	SOIC-8 SOIC-8	190 130	°C/W °C/W
$\theta_{JC}$	Thermal Resistance (Junction-to-Case)	Standard Board	SOIC-8	41 to 44	°C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	TSSOP-8 TSSOP-8	185 140	°C/W °C/W
$\theta_{JA}$	Thermal Resistance (Junction-to-Ambient)	0 lfpm 500 lfpm	DFN8 DFN8	129 84	°C/W °C/W
T <sub>sol</sub>	Wave Solder Pb Pb-Free	<2 to 3 sec @ 248°C <2 to 3 sec @ 260°C		265 265	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 4. 10ELT SERIES PECL INPUT DC CHARACTERISTICS	V <sub>CC</sub> = 5.0 V; GND = 0.0 V (Note 2)
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		-40°C			25°C			85°C			
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	3770		4110	3870		4190	3930		4265	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	3050		3500	3050		3520	3050		3555	mV
$V_{BB}$	Output Voltage Reference	3.57		3.7	3.65		3.75	3.69		3.81	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 3)	2.2		5.0	2.2		5.0	2.2		5.0	V
I <sub>IH</sub>	Input HIGH Current			255			175			175	μA
IIL	Input LOW Current	0.5			0.5			0.3			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

#### Table 5. 100ELT SERIES PECL INPUT DC CHARACTERISTICS V<sub>CC</sub> = 5.0 V; GND = 0.0 V (Note 4)

		<b>−40°C</b>		25°C			85°C				
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
V <sub>IH</sub>	Input HIGH Voltage (Single-Ended)	3835		4120	3835		4120	3835		4120	mV
V <sub>IL</sub>	Input LOW Voltage (Single-Ended)	3190		3525	3190		3525	3190		3525	mV
V <sub>BB</sub>	Output Voltage Reference	3.62		3.74	3.62		3.74	3.62		3.745	V
VIHCMR	Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 5)	2.2		5.0	2.2		5.0	2.2		5.0	V
I <sub>IH</sub>	Input HIGH Current			255			175			175	μA
Ι <sub>ΙL</sub>	Input LOW Current	0.5			0.5			0.5			μA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket o printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

4. Input parameters vary 1:1 with V\_{CC}. V\_{CC} can vary  $\pm$  0.25 V.

5. VIHCMR min varies 1:1 with GND, VIHCMR max varies 1:1 with VCC.

## Table 6. TTL OUTPUT DC CHARACTERISTICS $V_{CC}$ = 4.75 V to 5.25 V; $T_A$ = -40°C to 85°C)

Symbol	Characteristic	Condition	Min	Тур	Мах	Unit
V <sub>OH</sub>	Output HIGH Voltage	I <sub>OH</sub> = -3.0 mA	2.4		(Note 6)	V
V <sub>OL</sub>	Output LOW Voltage	I <sub>OL</sub> = 24 mA			0.5	V
I <sub>CCH</sub>	Power Supply Current			20	29	mA
I <sub>CCL</sub>	Power Supply Current			22	32	mA
I <sub>OS</sub>	Output Short Circuit Current		-150		-60	mA

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

6. Maximum level is  $V_{CC}$  – 0.7 by design.

		-40°C		25°C		85°C					
Symbol	Characteristic	Min	Тур	Max	Min	Тур	Max	Min	Тур	Max	Unit
f <sub>max</sub>	Maximum Toggle Frequency					100					MHz
t <sub>JITTER</sub>	Random Clock Jitter (RMS)					35					ps
t <sub>PLH</sub>	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
t <sub>PHL</sub>	Propagation Delay @ 1.5 V	2.0		5.5	2.0		5.5	2.0		5.5	ns
V <sub>PP</sub>	Input Swing (Note 8)	200		1000	200		1000	200		1000	mV
t <sub>r</sub> /t <sub>f</sub>	Output Rise/Fall Time (10–90%)					750					ps

#### AC CHARACTERISTICS $V_{CC} = 4.75$ V to 5.25 V; GND = 0.0 V (Note 7)

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

7. RL = 500  $\Omega$  to GND and CL = 20 pF to GND. Refer to Figure 2.

8. V<sub>PP</sub>(min) is the minimum input swing for which AC parameters are guaranteed. The device has a DC gain of -[]40.

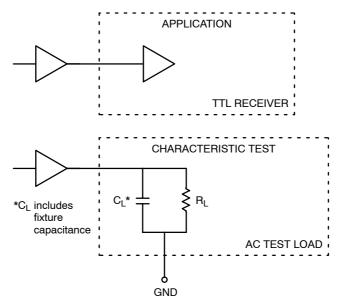


Figure 2. TTL Output Loading Used for Device Evaluation

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC10ELT21D	SOIC-8	98 Units / Rail
MC10ELT21DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC10ELT21DR2	SOIC-8	2500 / Tape & Reel
MC10ELT21DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC10ELT21DT	TSSOP-8	100 Units / Rail
MC10ELT21DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC10ELT21DTR2	TSSOP-8	2500 / Tape & Reel
MC10ELT21DTR2G	TSSOP-8 (Pb-Free)	2500 / Tape & Reel
MC10ELT21MNR4	DFN8	1000 / Tape & Reel
MC10ELT21MNR4G	DFN8 (Pb-Free)	1000 / Tape & Reel
MC100ELT21D	SOIC-8	98 Units / Rail
MC100ELT21DG	SOIC-8 (Pb-Free)	98 Units / Rail
MC100ELT21DR2	SOIC-8	2500 / Tape & Reel
MC100ELT21DR2G	SOIC-8 (Pb-Free)	2500 / Tape & Reel
MC100ELT21DT	TSSOP-8	100 Units / Rail
MC100ELT21DTG	TSSOP-8 (Pb-Free)	100 Units / Rail
MC100ELT21DTR2	TSSOP-8	2500 / Tape & Reel
MC100ELT21DTR2G	100ELT21DTR2G TSSOP-8 2500 / Tape & (Pb-Free)	
MC100ELT21MNR4	DFN8	1000 / Tape & Reel
MC100ELT21MNR4G	DFN8 (Pb–Free)	1000 / Tape & Reel

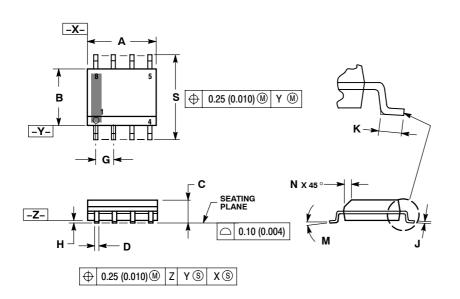
†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### **Resource Reference of Application Notes**

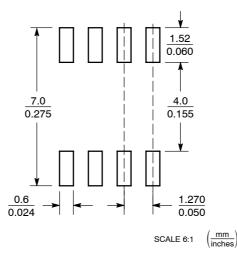
needen ee n		ciciliee of Application Noted
AN1405/D	-	ECL Clock Distribution Techniques
AN1406/D	-	Designing with PECL (ECL at +5.0 V)
AN1503/D	-	ECLinPS <sup>™</sup> I/O SPiCE Modeling Kit
AN1504/D	-	Metastability and the ECLinPS Family
AN1568/D	-	Interfacing Between LVDS and ECL
AN1672/D	-	The ECL Translator Guide
AND8001/D	-	Odd Number Counters Design
AND8002/D	-	Marking and Date Codes
AND8020/D	-	Termination of ECL Logic Devices
AND8066/D	_	Interfacing with ECLinPS
AND8090/D	_	AC Characteristics of ECL Devices

## PACKAGE DIMENSIONS

SOIC-8 NB CASE 751-07 **ISSUE AH** 



**SOLDERING FOOTPRINT\*** 



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

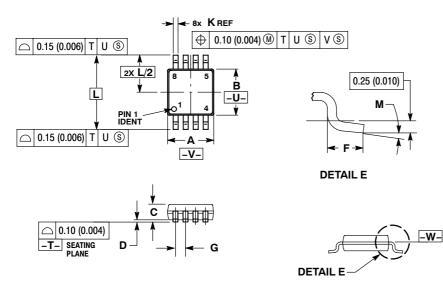
- NOTES:
   DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: MILLIMETER.
   DIMENSION A AND B DO NOT INCLUDE MOLD PROTRUSION.
   MAXIMUM MOLD PROTRUSION 0.15 (0.006) DEB SIDE

- MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
   DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.
   751-01 THRU 751-06 ARE OBSOLETE. NEW STANDARD IS 71 07
- STANDARD IS 751-07.

	MILLIN	IETERS	INC	HES	
DIM	MIN	MAX	MIN	MAX	
Α	4.80	5.00	0.189	0.197	
в	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.053	0.069	
D	0.33	0.51	0.013	0.020	
G	1.27	7 BSC	0.050 BSC		
н	0.10	0.25	0.004	0.010	
J	0.19	0.25	0.007	0.010	
к	0.40	1.27	0.016	0.050	
м	0 °	8 °	0 °	8 °	
Ν	0.25	0.50	0.010	0.020	
S	5.80	6.20	0.228	0.244	

## PACKAGE DIMENSIONS

TSSOP-8 **DT SUFFIX** PLASTIC TSSOP PACKAGE CASE 948R-02 **ISSUE A** 

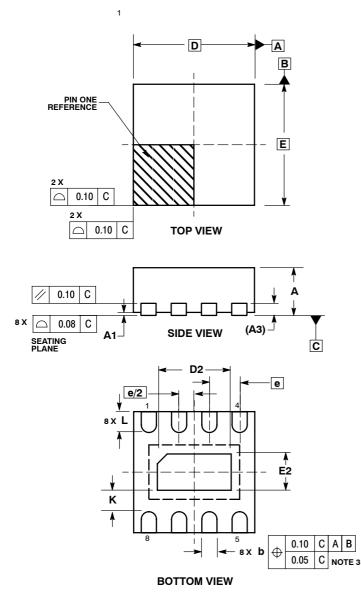


- NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: MILLIMETER.
- DIMENSION A DOES NOT INCLUDE MOLD FLASH. PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15
- GATE DOINS SHALL NOT EXCEED 0.13
   (0.006) PER SIDE.
   DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION SHALL NOT EXCEED 0.25 (0.010) DED 015 PER SIDE. 5. TERMINAL NUMBERS ARE SHOWN FOR
- REFERENCE ONLY.
  DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	2.90	3.10	0.114	0.122
В	2.90	3.10	0.114	0.122
C	0.80	1.10	0.031	0.043
D	0.05	0.15	0.002	0.006
F	0.40	0.70	0.016	0.028
G	0.65 BSC		0.026 BSC	
K	0.25	0.40	0.010	0.016
L	4.90 BSC		0.193 BSC	
M	0°	6 °	0°	6°

#### PACKAGE DIMENSIONS

DFN8 CASE 506AA-01 ISSUE D



NOTES:

 DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

- CONTROLLING DIMENSION: MILLIMETERS.
   DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN
- 0.25 AND 0.30 MM FROM TERMINAL.
   COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

	MILLIMETERS			
DIM	MIN	MAX		
Α	0.80	1.00		
A1	0.00	0.05		
A3	0.20 REF			
b	0.20	0.30		
D	2.00 BSC			
D2	1.10	1.30		
Е	2.00 BSC			
E2	0.70	0.90		
е	0.50 BSC			
К	0.20			
L	0.25	0.35		

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